

Single Phase Bridge (Power Modules), 25/35 A


MB
FEATURES

- Universal, 3 way terminals:
Push-on, wrap around or solder
- High thermal conductivity package, electrically insulated case
- Center hole fixing
- Excellent power/volume ratio
- Nickel plated terminals solderable using lead (Pb)-free solder; Solder Alloy Sn/Ag/Cu (SAC305); Solder temperature 260 to 275 °C
- RoHS compliant
- Designed and qualified for industrial level


**RoHS
COMPLIANT**
PRODUCT SUMMARY

$I_{T(AV)}$	25/35 A
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DESCRIPTION

A range of extremely compact, encapsulated single phase bridge rectifiers offering efficient and reliable operation. They are intended for use in general purpose and instrumentation applications.

MAJOR RATINGS AND CHARACTERISTICS

SYMBOL	CHARACTERISTICS	26MB-A	36MB-A	UNITS
I_o		25	35	A
	T_c	65	60	°C
I_{FSM}	50 Hz	400	475	A
	60 Hz	420	500	
I^2t	50 Hz	790	1130	A ² s
	60 Hz	725	1030	
V_{RRM}	Range	200 to 1200		V
T_J		- 55 to 150		°C

ELECTRICAL SPECIFICATIONS
VOLTAGE RATINGS

TYPE NUMBER	VOLTAGE CODE	V_{RRM} , MAXIMUM REPETITIVE PEAK REVERSE VOLTAGE V	V_{RSM} , MAXIMUM NON-REPETITIVE PEAK REVERSE VOLTAGE V	I_{RRM} MAXIMUM AT T_J MAXIMUM
26MB..A 36MB..A	20	200	275	2
	40	400	500	
	60	600	725	
	80	800	900	
	100	1000	1100	
	120	1200	1300	

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FORWARD CONDUCTION							
PARAMETER	SYMBOL	TEST CONDITIONS		26MB-A	36MB-A	UNITS	
Maximum DC output current at case temperature	I _o	Resistive or inductive load		25	35	A	
		Capacitive load		20	28		
				65	60	°C	
Maximum peak, one-cycle non-repetitive forward current	I _{FSM}	t = 10 ms	No voltage reapplied	Initial T _J = T _J maximum	400	475	A
		t = 8.3 ms					
		t = 10 ms	100 % V _{RRM} reapplied		335	400	
		t = 8.3 ms					
Maximum I ² t for fusing	I ² t	t = 10 ms	No voltage reapplied	Initial T _J = T _J maximum	790	1130	A ² s
		t = 8.3 ms					
		t = 10 ms	100 % V _{RRM} reapplied		560	800	
		t = 8.3 ms					
Maximum I ² √t for fusing	I ² √t	I ² t for time t _x = I ₂ √t × √t _x ; 0.1 ≤ t _x ≤ 10 ms, V _{RRM} = 0 V		5.6	11.3	kA ² √s	
Low level value of threshold voltage	V _{F(TO)1}	(16.7 % × π × I _{F(AV)}) < I < π × I _{F(AV)} , T _J maximum		0.76	0.79	V	
High level value of threshold voltage	V _{F(TO)2}	(I > π × I _{F(AV)}), T _J maximum		0.92	0.96		
Low level forward slope resistance	r _{t1}	(16.7 % × π × I _{F(AV)}) < I < π × I _{F(AV)} , T _J maximum		6.8	5.8	mΩ	
High level forward slope resistance	r _{t2}	(I > π × I _{F(AV)}), T _J maximum		5.0	4.5		
Maximum forward voltage drop	V _{FM}	T _J = 25 °C, I _{FM} = 40 A _{pk} (26MB)		1.11	1.14	V	
		T _J = 25 °C, I _{FM} = 55 A _{pk} (36MB)					
Maximum DC reverse current	I _{RRM}	T _J = 25 °C, per diode at V _{RRM}		10		μA	
RMS isolation voltage base plate	V _{INS}	f = 50 Hz, t = 1 s		2700		V	

THERMAL AND MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS		26MB-A	36MB-A	UNITS
Junction and storage temperature range	T _J , T _{Stg}			- 55 to 150		°C
Maximum thermal resistance junction to case per bridge	R _{thJC}			1.7	1.2	K/W
Maximum thermal resistance, case to heatsink	R _{thCS}	Mounting surface, smooth, flat and greased		0.2		
Approximate weight				20		g
Mounting torque ± 10 %		Bridge to heatsink		2.0		Nm

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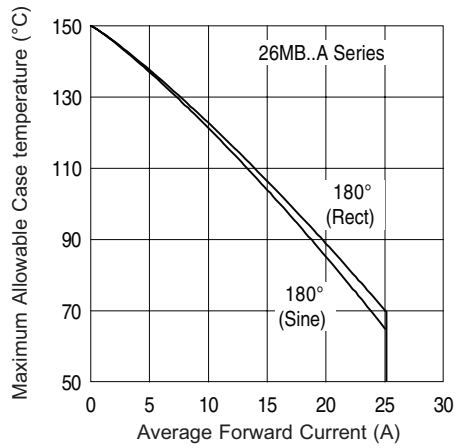


Fig. 1 - Current Ratings Characteristics

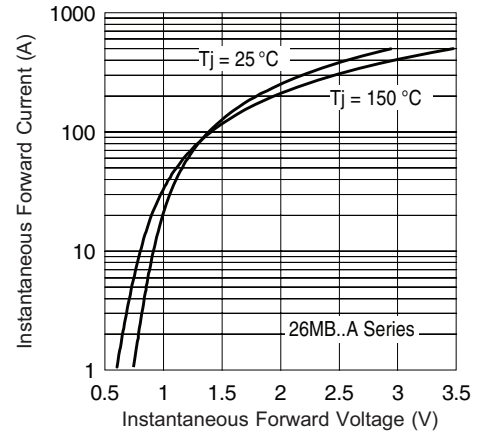
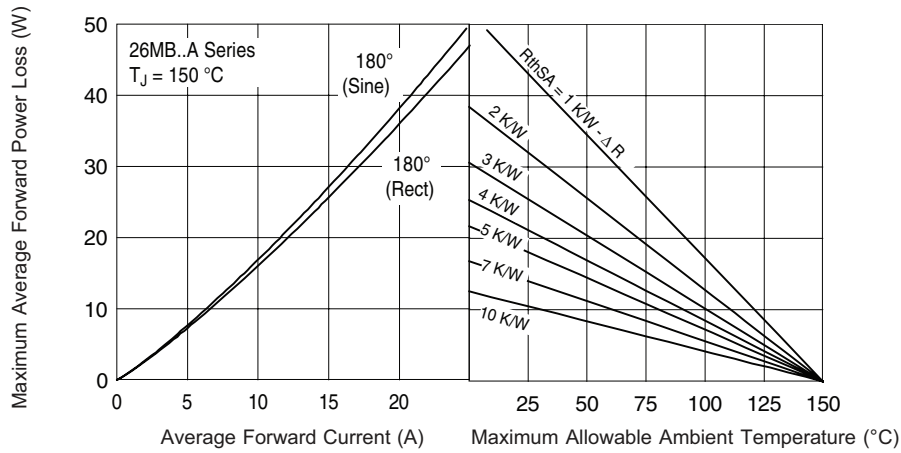

 Fig. 2 - Forward Voltage Drop Characteristics
Maximum Allowable Ambient Temperature


Fig. 3 - Total Power Loss Characteristics

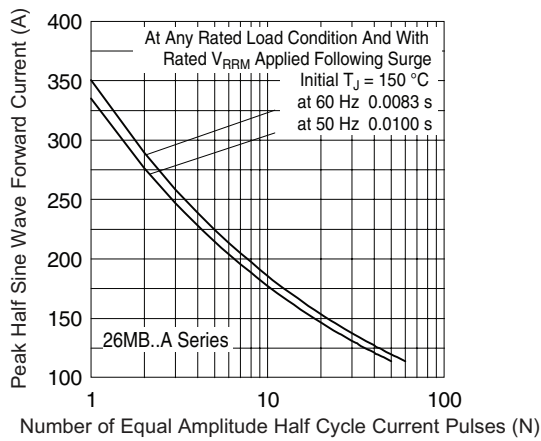


Fig. 4 - Maximum Non-Repetitive Surge Current

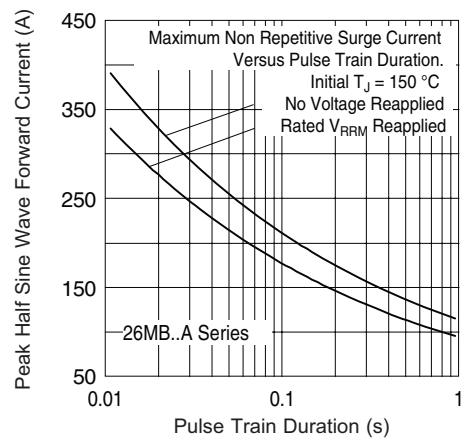


Fig. 5 - Maximum Non-Repetitive Surge Current

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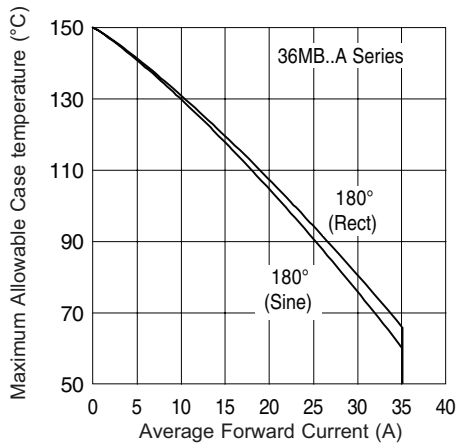


Fig. 6 - Current Ratings Characteristics

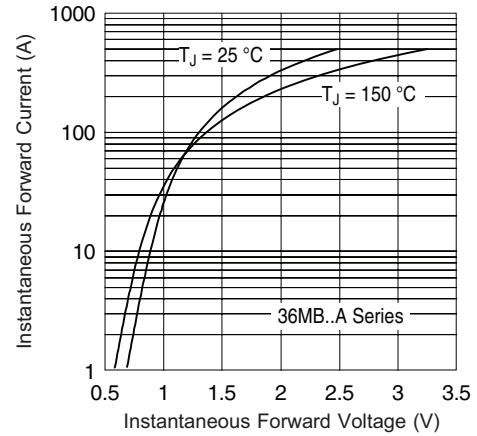


Fig. 7 - Forward Voltage Drop Characteristics

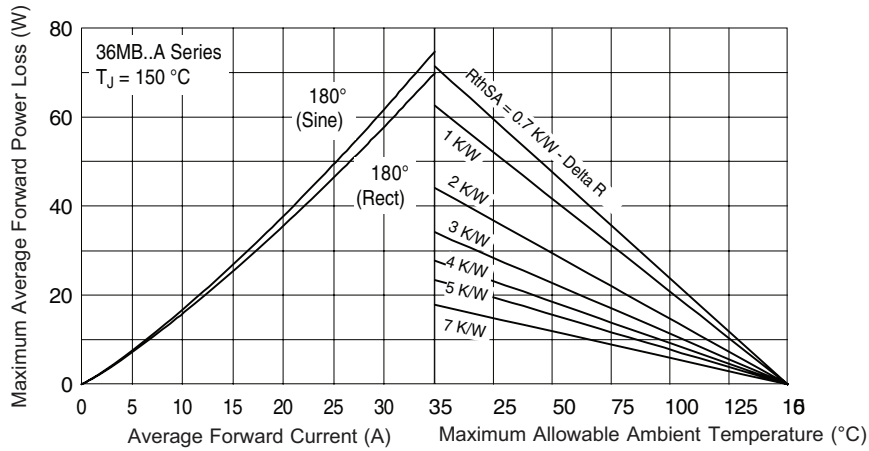


Fig. 8 - Total Power Loss Characteristics

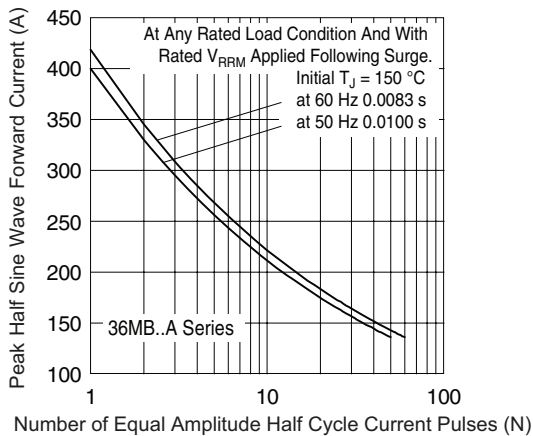


Fig. 9 - Maximum Non-Repetitive Surge Current

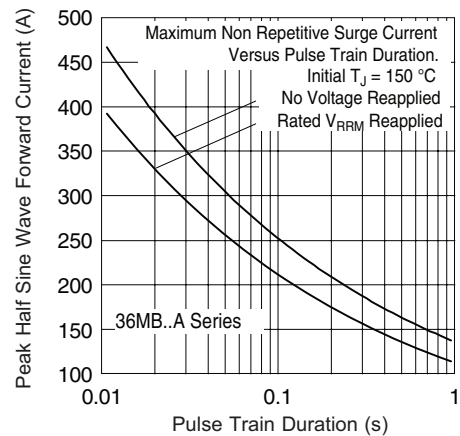
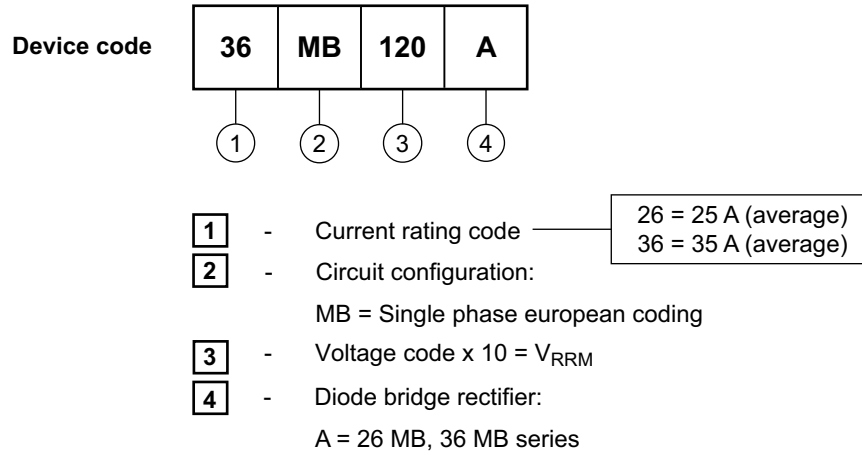
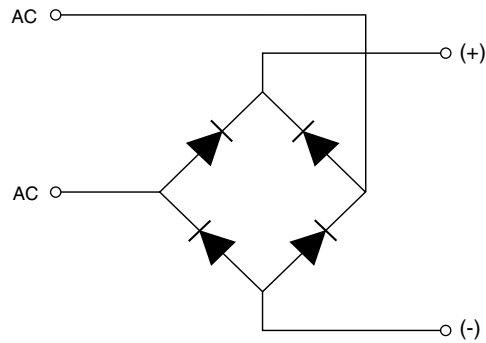


Fig. 10 - Maximum Non-Repetitive Surge Current

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ORDERING INFORMATION TABLE

CIRCUIT CONFIGURATION


LINKS TO RELATED DOCUMENTS	
Dimensions	http://www.vishay.com/doc?95326

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